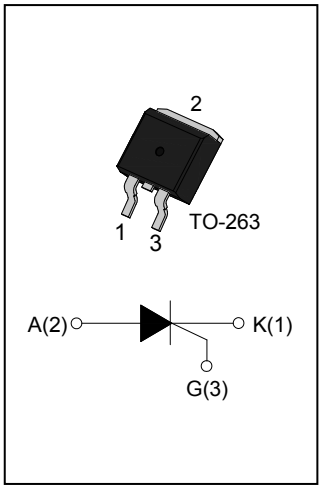
JCTx20 Series 20A SCRs

Rev.6.0

DESCRIPTION:

With high ability to withstand the shock loading of large current, JCTx20 SCRs provide high dv/dt rate with strong resistance to electromagnetic interference. They are especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc. Package TO-263 is RoHS compliant. (2011/65/EU)



MAIN FEATURES

Symbol	JCT620	JCT820
V_{DRM}/ V_{RRM}	600V	800V
$I_{T(RMS)}$	20A	
I_{GT}	≤25mA	

ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T_{stg}	-40-150	℃
Operating junction temperature range		T_j	-40-150	℃
Repetitive peak off-state voltage(T_j=25℃)		V_{DRM}	600/800	V
Repetitive peak reverse voltage(T_j=25℃)		V_{RRM}	600/800	V
RMS on-state current	TO-263 (T_C=80℃)	$I_{T(RMS)}$	20	A
Non repetitive surge peak on-state current (tp=10ms)		I_{TSM}	250	A
I^2t value for fusing (tp=10ms)		I^2t	312.5	A^2s
Critical rate of rise of on-state current (I_G=2×I_{GT})		dI/dt	50	A/μs
Peak gate current		I_{GM}	4	A
Average gate power dissipation		$P_{G(AV)}$	1	W
Peak gate power		P_{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j=25℃ unless otherwise specified)

Symbol	Test Condition	Value			Unit
		MIN.	TYP.	MAX.	
I_{GT}	V_D=12V R_L=33Ω	-	-	25	mA
V_{GT}		-	-	1.3	V
V_{GD}	V_D=V_{DRM} T_j=150℃ R_L=3.3KΩ	0.2	-	-	V
I_L	I_G=1.2I_{GT}	-	-	70	mA
I_H	I_T=500mA	-	-	60	mA
dV/dt	V_D=2/3V_{DRM} Gate Open T_j=150℃	200	-	-	V/μs

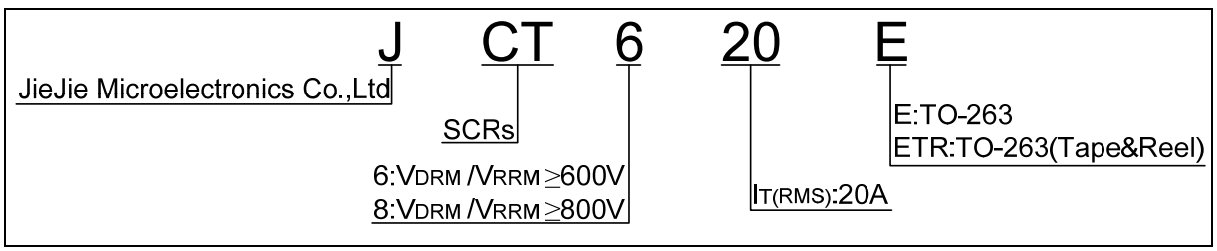
STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V_{TM}	I_{TM}=40A tp=380μs	T_j=25℃	1.55	V
I_{DRM}	V_D=V_{DRM} V_R=V_{RRM}	T_j=25℃	5	μA
I_{RRM}		T_j=150℃	4	mA

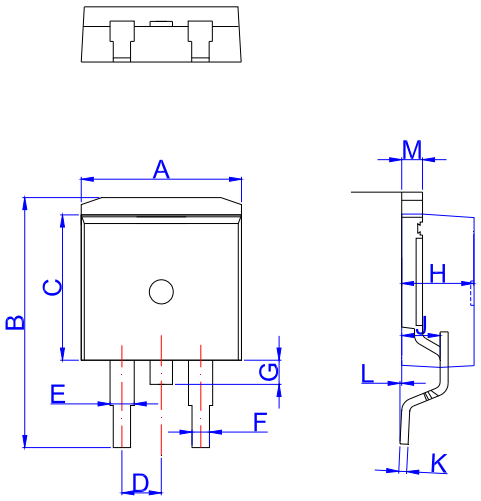
THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-263	2.5	℃/W
$R_{th(j-a)}$	junction to ambient		45	

ORDERING INFORMATION



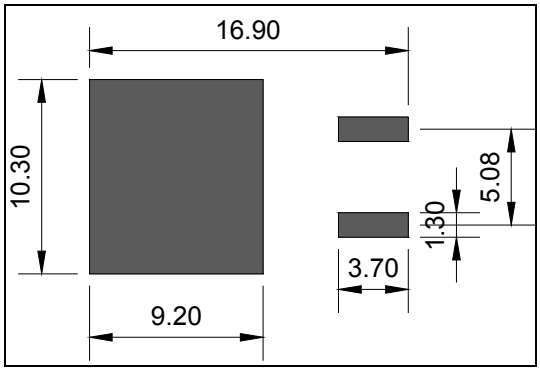
PACKAGE MECHANICAL DATA



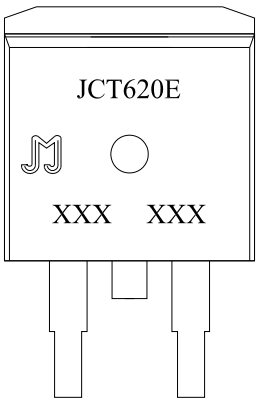
TO-263

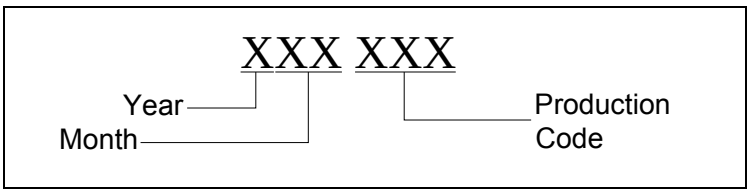
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053

FOOTPRINT-TO-263 (dimensions in mm)



MARKING





PACKAGE INFORMATION

PACKAGE	OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON
TO-263	TUBE	50	1,000	6,000
TO-263	TUBE	50	1,000	8,000
PACKAGE	**OUTLINE**	**REEL (PCS)**	**PER CARTON (PCS)**	**TAPE & REEL**
TO-263	TAPING	800	4,000	13 inch

FIG.1: Maximum power dissipation versus RMS on-state current

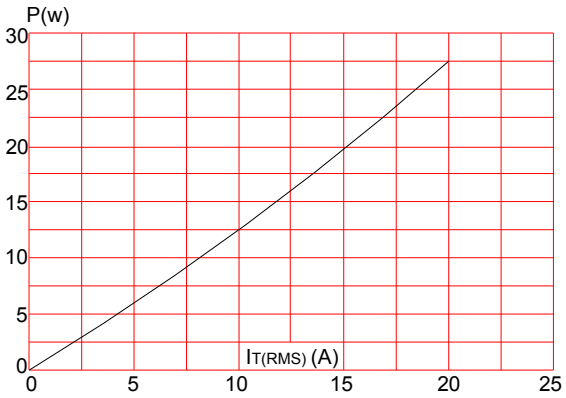


FIG.2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness:35μm)(full cycle)

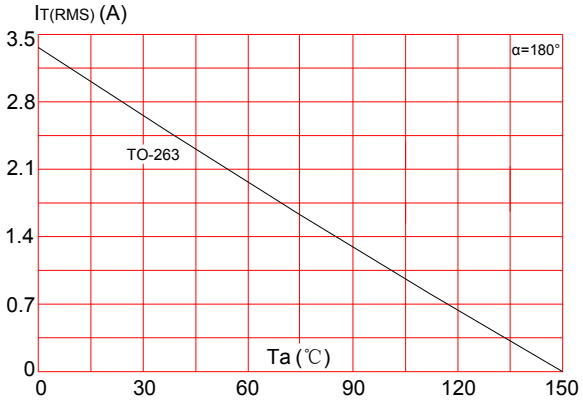


FIG.3: Surge peak on-state current versus number of cycles

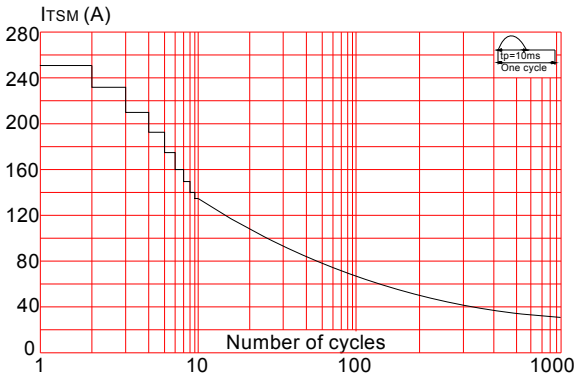


FIG.4: On-state characteristics (maximum values)

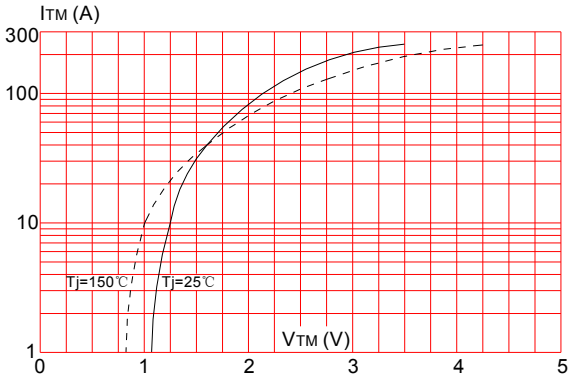


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponging value of I^2t

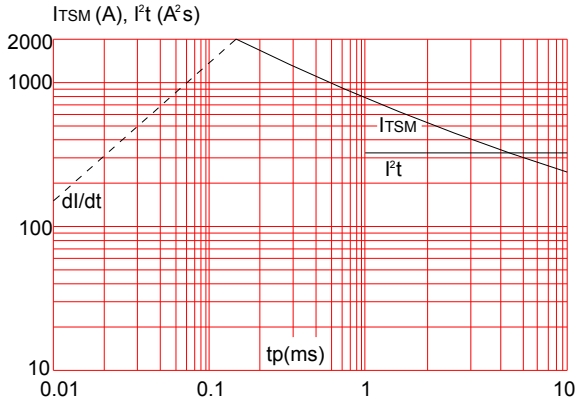
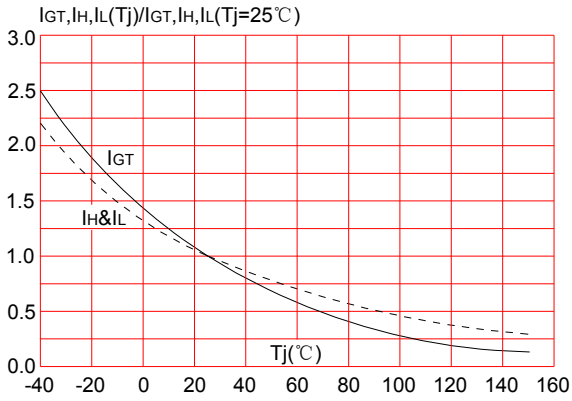
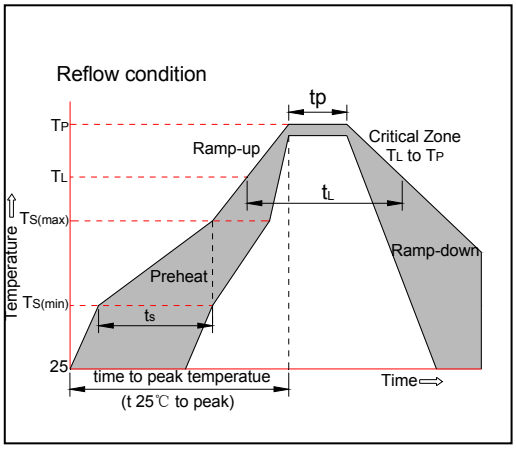


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max ($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃



Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co.,Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement. Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information.

This document is the sixth version which is made in 27-Jan.-2019. This document supersedes and replaces all information previously supplied.

is a registered trademark of Jiangsu JieJie Microelectronics Co.,Ltd.